

Appl. No. 10/773,383  
Office Action mailed 04/06/2007

In the Claims

Claims 1-31 [canceled].

32. [Currently Amended] A temperature sensing apparatus fabrication method of sensing temperature of an electronic device workpiece comprising:  
providing an electronic device workpiece;  
forming a cavity in an electronic device workpiece;  
providing a temperature sensing device within the cavity and in a configuration to  
sense temperature of the electronic device workpiece;  
supporting [[a]] the temperature sensing device using the electronic device  
workpiece;  
providing an electrical interconnect upon a surface of the electronic device  
workpiece; and  
electrically coupling the electrical interconnect with the temperature sensing device;  
and  
sensing temperature of the electronic device workpiece using the temperature  
sensing device.

33. [Currently Amended] The method according to claim 32 further comprising  
wherein the electrically coupling comprises wire bonding the electrical interconnect and the  
temperature sensing device.

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34. [Cancelled].

35. [Currently Amended] The method according to claim [[34]] 32 wherein the forming the cavity comprises anisotropically etching the electronic device workpiece.

36. [Currently Amended] The method according to claim [[34]] 32 wherein the forming the cavity comprises isotropically etching the electronic device workpiece.

37. [Original] The method according to claim 32 further comprising forming the temperature sensing device.

38. [Original] The method according to claim 37 wherein the forming the temperature sensing device comprises forming a resistance temperature device.

39. [Original] The method according to claim 32 further comprising electrically coupling the electrical interconnect with external circuitry.

40. [Original] The method according to claim 32 further comprising electrically coupling the temperature sensing device with an edge of the electronic device workpiece using the electrical interconnect.

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41. [Original] The method according to claim 32 wherein the providing the electrical interconnect comprises forming a conductive trace.

42. [Original] The method according to claim 32 further comprising contacting the electrical interconnect with the temperature sensing device.

43. [Previously Presented] The method according to claim 32 wherein the sensing comprises sensing temperature of the electronic device workpiece comprising a semiconductive wafer.

Claims 44-52 [canceled].

53. [Currently Amended] A temperature sensing apparatus fabrication method of ~~sensing temperature of an electronic device workpiece comprising:~~  
providing an electronic device workpiece;  
forming a plurality of temperature sensing device devices over the electronic device workpiece, the forming including providing the temperature sensing device devices being configured to sense temperature in three dimensions of in a temperature sensing relation with the electronic device workpiece; and  
sensing the temperature of the electronic device workpiece using the temperature sensing device.

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54. [Currently Amended] The method according to claim 53 further comprising:  
providing an electrical interconnect upon the electronic device workpiece; and  
electrically coupling the electrical interconnect with at least one of the temperature  
sensing device devices.
55. [Original] The method according to claim 54 wherein the providing the  
electrical interconnect comprises forming a conductive trace.
56. [Currently Amended] The method according to claim 54 wherein the  
electrically coupling comprises wire bonding the electrical interconnect and the at least one  
of the temperature sensing device devices.
57. [Currently Amended] The method according to claim 54 wherein the  
electrically coupling includes contacting the electrical interconnect and the at least one of  
the temperature sensing device devices.
58. [Currently Amended] The method according to claim 53 further comprising:  
forming a cavity in the electronic device workpiece; and  
providing at least one of the temperature sensing device devices within the cavity.

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59. [Original] The method according to claim 58 wherein the forming the cavity comprises anisotropically etching the electronic device workpiece.

60. [Currently Amended] The method according to claim 53 wherein the forming comprises forming the temperature sensing devices individually comprising a resistance temperature device.

61. [Cancelled].

62. [Currently Amended] A temperature sensing apparatus fabrication method of sensing temperature of an electronic device workpiece comprising:  
providing an electronic device workpiece;  
supporting a temperature sensing device using the an electronic device workpiece;  
providing the temperature sensing device in a temperature sensing relation relationship with the electronic device workpiece;  
providing an electrical interconnect upon a surface of the electronic device workpiece; and  
electrically coupling the electrical interconnect with the temperature sensing device comprising wire bonding the electrical interconnect and the temperature sensing device.

63. [Cancelled].

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64. [Cancelled].

65. [Original] The method according to claim 62 further comprising:  
forming a cavity in the electronic device workpiece; and  
providing the temperature sensing device within the cavity.

66. [Original] The method according to claim 65 wherein the forming the cavity  
comprises anisotropically etching the electronic device workpiece.

67. [Previously Presented] The method according to claim 62 further comprising  
forming the temperature sensing device upon the electronic device workpiece.

68. [Original] The method according to claim 62 further comprising electrically  
coupling the electrical interconnect with circuitry external to the electronic device  
workpiece.

69. [Original] The method according to claim 62 further comprising electrically  
coupling the temperature sensing device with an edge of the electronic device workpiece  
using the electrical interconnect.

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70. [Original] The method according to claim 62 wherein the providing the electrical interconnect comprises forming a conductive trace.

71. [Currently Amended] A temperature sensing method comprising:  
~~supporting a plurality of temperature sensing device devices using a wafer, and wherein the temperature sensing devices are individually in a temperature sensing relationship with respect to the wafer;~~

~~providing the temperature sensing device in a temperature sensing relationship with respect to the wafer;~~

exposing the wafer and the temperature sensing device devices to process conditions effective to form at least one electronic device; and

sensing [[a]] temperature of the wafer in three dimensions of the wafer using the temperature sensing device devices during the exposing.

72. [Previously Presented] The method of claim 71 further comprising adjusting the process conditions responsive to the sensing.

73. [Previously Presented] The method of claim 71 further comprising sensing the temperature of the wafer at a plurality of positions covering substantially an entirety of a surface of the wafer.

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74. [Cancelled].

75. [Currently Amended] The method of claim 71 wherein the wafer comprises a production wafer, and further comprising forming the at least one electronic device using the wafer ~~responsive to~~ during the exposing.

76. [Currently Amended] The method according to claim 32 wherein the providing the electronic device workpiece comprises ~~providing a wafer comprising silicon a silicon wafer.~~

77. [Currently Amended] The method according to claim 32 ~~wherein the sensing comprises sensing further comprising configuring the temperature sensing device to sense~~ the temperature of the electronic device workpiece during fabrication of an electronic device using the electronic device workpiece.

78. [Previously Presented] The method according to claim 53 wherein the providing the electronic device workpiece comprises providing a wafer comprising silicon.

79. [Currently Amended] The method according to claim 53 ~~wherein the sensing comprises sensing wherein the temperature sensing devices are individually configured to~~

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sense the temperature of the electronic device workpiece during fabrication of an electronic device using the electronic device workpiece.

80. [Currently Amended] The method according to claim 62 wherein the providing the electronic device workpiece comprises providing a wafer comprising silicon a silicon wafer

81. [Currently Amended] The method according to claim 62 further comprising sensing wherein the temperature sensing device is configured to sense temperature of the electronic device workpiece during fabrication of an electronic device using the electronic device workpiece.

82. [Currently Amended] The method of claim 71 wherein the supporting comprises supporting the temperature sensing device devices using the wafer comprising silicon.

83. [Previously Presented] The method of claim 71 wherein the sensing the temperature comprises sensing the temperature of the wafer during fabrication of an electronic device using the wafer.

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84. [New] A temperature sensing apparatus fabrication method comprising:  
providing an electronic device workpiece;  
forming a temperature sensing device over the electronic device workpiece, the forming including providing the temperature sensing device in a temperature sensing relation with the electronic device workpiece;  
providing an electrical interconnect upon the electronic device workpiece;  
electrically coupling the electrical interconnect with the temperature sensing device;  
and  
wherein the electrically coupling comprises wire bonding the electrical interconnect and the temperature sensing device.

85. [New] A temperature sensing apparatus fabrication method comprising:  
providing an electronic device workpiece;  
forming a cavity in the electronic device workpiece; and  
forming a temperature sensing device within the cavity, the temperature sensing device being configured to sense temperature of the electronic device workpiece.

86. [New] The method according to claim 85 wherein the forming the cavity comprises anisotropically etching the electronic device workpiece.

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87. [New] A temperature sensing apparatus fabrication method comprising:  
forming a cavity in an electronic device workpiece;  
supporting a temperature sensing device using the electronic device workpiece, the  
supporting comprising providing the temperature sensing device within the cavity in a  
temperature sensing relationship with the electronic device workpiece;  
providing an electrical interconnect upon a surface of the electronic device  
workpiece; and  
electrically coupling the electrical interconnect with the temperature sensing device.

88. [New] The method according to claim 87 wherein the forming the cavity  
comprises anisotropically etching the electronic device workpiece.

89. [New] A temperature sensing method comprising:  
supporting a temperature sensing device using a wafer;  
exposing the wafer and the temperature sensing device to process conditions  
effective to form at least one electronic device;  
sensing a temperature of the wafer using the temperature sensing device during the  
exposing; and  
during the exposing, forming the at least one electronic device using the wafer.